

SOT186

plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 lead TO-220 "full pack" exposed tabs

10 February 2016 Package information

1. Package summary

Terminal position code S (single)

Package type descriptive code TO-220F; SC-67
Package type industry code TO-220F; SC-67

Package style descriptive code SFM (single-ended flange mount)

Package style suffix code NA (not applicable)

Package body material type P (plastic)

Mounting method type H (heatsink mount)

Issue date 12-3-2002

Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	16.4	-	16.7	17	mm
E	package width	9.6	-	9.9	10.2	mm
Α	seated height	4	-	4.2	4.4	mm
е	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	3	-	



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2. Package outline

Plastic single-ended package; isolated heatsink mounted; **SOT186** 1 mounting hole; 3-lead TO-220 'full pack' exposed tabs m D_1 mounting base D ⊕ w M е 5 10 mm Lummandumum scale **DIMENSIONS** (mm are the original dimensions) L₁⁽¹⁾ L_2 UNIT D D_1 Ε E₁ e₁ L Ρ Q b_1 q 4.4 2.9 0.9 1.5 0.55 17.0 7.9 10.2 5.7 14.3 4.8 0.9 3.2 1.4 4.4 5.08 2.54 10 0.4 4.0 2.5 0.7 1.3 0.38 16.4 9.6 5.3 13.5 0.5 3.0 4.0 Note 1. Terminal dimensions within this zone are uncontrolled. Terminals in this zone are not tinned.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT186		3-lead TO-220F	SC-67			-99-09-13 02-03-12

Fig. 1. Package outline TO-220F; SC-67 (SOT186)

2/4

NXP Semiconductors SOT186

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3. Legal information

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3/4

NXP Semiconductors SOT186

plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 lead TO-220 "full pack" exposed tabs

4. Contents

1.	Package summary	1
2.	Package outline	. 2
3.	Legal information	. 3
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